- Members of the Texas Instruments *Widebus*™ Family
- *EPIC*™ (Enhanced-Performance Implanted CMOS) Process
- Inputs Are TTL-Voltage Compatible
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

SN54AHCT16374 . . . WD PACKAGE
SN74AHCT16374 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)

1$\overline{OE}$	1	48	1CLK
1Q1	2	47	1D1
1Q2	3	46	1D2
GND	4	45	GND
1Q3	5	44	1D3
1Q4	6	43	1D4
V_{CC}	7	42	V_{CC}
1Q5	8	41	1D5
1Q6	9	40	1D6
GND	10	39	GND
1Q7	11	38	1D7
1Q8	12	37	1D8
2Q1	13	36	2D1
2Q2	14	35	2D2
GND	15	34	GND
2Q3	16	33	2D3
2Q4	17	32	2D4
V_{CC}	18	31	V_{CC}
2Q5	19	30	2D5
2Q6	20	29	2D6
GND	21	28	GND
2Q7	22	27	2D7
2Q8	23	26	2D8
2$\overline{OE}$	24	25	2CLK

description

The 'AHCT16374 devices are 16-bit edge-triggered D-type flip-flops with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

These devices can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels at the data (D) inputs.
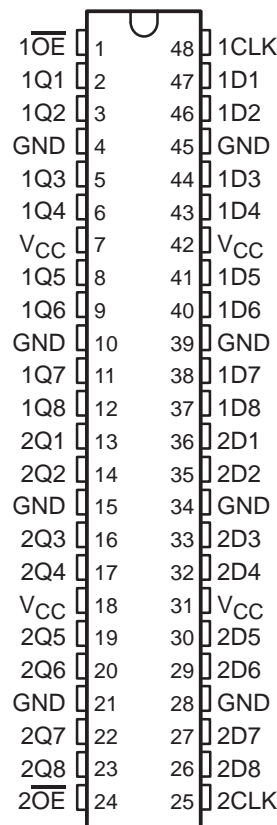
A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

$\overline{OE}$ does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The SN54AHCT16374 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74AHCT16374 is characterized for operation from –40°C to 85°C.

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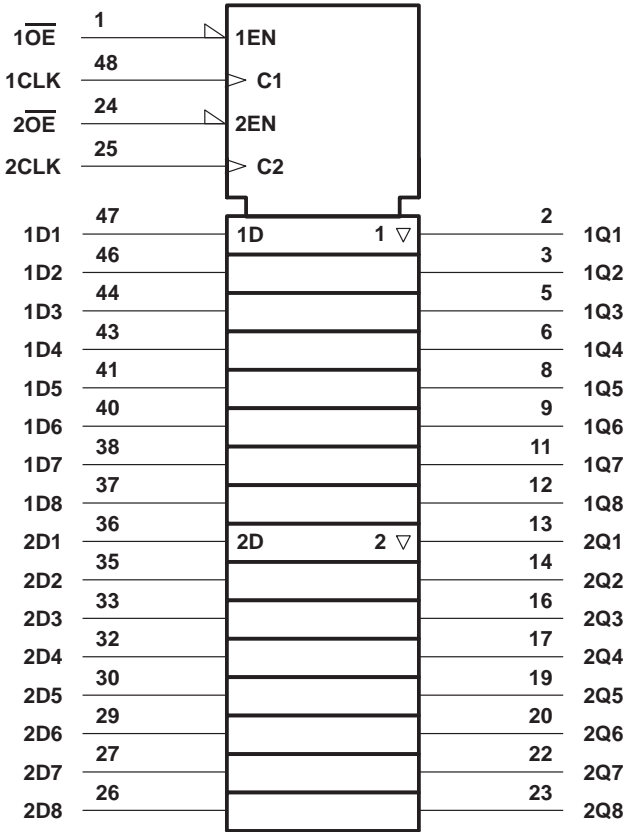
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SN54AHCT16374, SN74AHCT16374
16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOPS
WITH 3-STATE OUTPUTS

SCLS337I – MARCH 1996 – REVISED FEBRUARY 2000

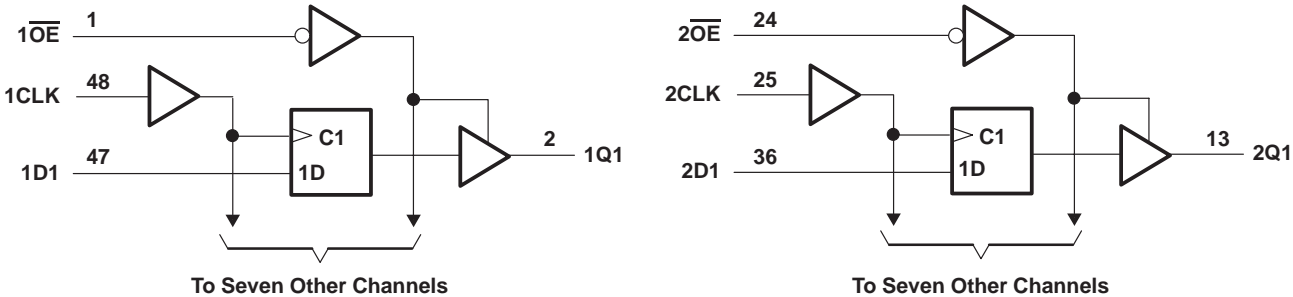**FUNCTION TABLE**
(each 8-bit flip-flop)

	INPUTS		OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	Q_0
H	X	X	Z

logic symbol[†]

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . –0.5 V to 7 V

Input voltage range, V_I (see Note 1) . . . . –0.5 V to 7 V

Output voltage range, V_O (see Note 1) . . . . –0.5 V to V_{CC} + 0.5 V

Input clamp current, I_{IK} ($V_I < 0$) . . . . –20 mA

Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) . . . . ±20 mA

Continuous output current, I_O ($V_O = 0$ to V_{CC}) . . . . ±25 mA

Continuous current through each V_{CC} or GND . . . . ±75 mA

Package thermal impedance, θ_{JA} (see Note 2): DGG package . . . . 70°C/W

DGV package . . . . 58°C/W

DL package . . . . 63°C/W

Storage temperature range, T_{stg} . . . . –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

		SN54AHCT16374		SN74AHCT16374		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	5.5	0	5.5	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–8		–8	mA
I_{OL}	Low-level output current		8		8	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		20		20	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	$T_A = 25°C$			SN54AHCT16374		SN74AHCT16374		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		$I_{OH} = -50\ \mu A$	4.5 V	4.4	4.5		4.4		4.4		V
		$I_{OH} = -8\ mA$		3.94			3.8		3.8		
V_{OL}		$I_{OL} = 50\ \mu A$	4.5 V			0.1		0.1		0.1	V
		$I_{OL} = 8\ mA$				0.36		0.44		0.44	
I_I		$V_I = V_{CC}$ or GND	0 V to 5.5 V			±0.1		±1*		±1	μA
I_{OZ}		$V_O = V_{CC}$ or GND, $V_I = V_{IH}$ or V_{IL}	5.5 V			±0.25		±2.5		±2.5	μA
I_{CC}		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		40		40	μA
$\Delta I_{CC}†$		One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			1.35		1.5		1.5	mA
C_i		$V_I = V_{CC}$ or GND	5 V		2.5	10				10	pF
C_o		$V_O = V_{CC}$ or GND	5 V		3.5						pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested at $V_{CC} = 0$ V.
† This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, $V_{CC} = 5\ V \pm 0.5\ V$ (unless otherwise noted) (see Figure 1)

		$T_A = 25°C$		SN54AHCT16374		SN74AHCT16374		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, CLK high or low	6.5		6.5		6.5		ns
t_{su}	Setup time, data before CLK↑	2.5		2.5		2.5		ns
t_h	Hold time, data after CLK↑	2.5		2.5		2.5		ns

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**switching characteristics over recommended operating free-air temperature range,
V_{CC} = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54AHCT16374		SN74AHCT16374		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			C_L = 15 pF	90*	140*		80*		110		MHz
			C_L = 50 pF	85	130		75		75		
t_{PLH}	CLK	Q	C_L = 15 pF		6.5*	9.4*	1*	10.5*	1	10.5	ns
t_{PHL}					6.5*	9.4*	1*	10.5*	1	10.5	
t_{PZH}	$\overline{OE}$	Q	C_L = 15 pF		6.5*	9.5*	1*	10.5*	1	10.5	ns
t_{PZL}					6.5*	9.5*	1*	10.5*	1	10.5	
t_{PHZ}	$\overline{OE}$	Q	C_L = 15 pF		6.2*	10.2*	1*	11*	1	11	ns
t_{PLZ}					6.2*	10.2*	1*	11*	1	11	
t_{PLH}	CLK	Q	C_L = 50 pF		7.3	10.4	1	11.5	1	11.5	ns
t_{PHL}					7.1	10.4	1	11.5	1	11.5	
t_{PZH}	$\overline{OE}$	Q	C_L = 50 pF		6.2	10.5	1	11.5	1	11.5	ns
t_{PZL}					5.1	10.5	1	11.5	1	11.5	
t_{PHZ}	$\overline{OE}$	Q	C_L = 50 pF		7.1	11.2	1	12	1	12	ns
t_{PLZ}					7.9	11.2	1	12	1	12	
$t_{sk(o)}$			C_L = 50 pF			1**				1	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.
** On products compliant to MIL-PRF-38535, this parameter does not apply.

noise characteristics, V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

PARAMETER		SN74AHCT16374			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.36	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		−0.1	−0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		4.7		V
$V_{IH(D)}$	High-level dynamic input voltage	2			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.8	V

NOTE 4:   Characteristics are for surface-mount packages only.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	No load,	f = 1 MHz	27	pF

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PARAMETER MEASUREMENT INFORMATION

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{CC}
t_{PHZ}/t_{PZH}	GND
Open Drain	V_{CC}

LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS

LOAD CIRCUIT FOR
3-STATE AND OPEN-DRAIN OUTPUTS

VOLTAGE WAVEFORMS
PULSE DURATION

VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 3 ns, t_f ≤ 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGE OPTION ADDENDUM

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74AHCT16374DGGR	Active	Production	TSSOP (DGG) | 48	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT16374
SN74AHCT16374DGGR.A	Active	Production	TSSOP (DGG) | 48	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT16374
SN74AHCT16374DGVR	Active	Production	TVSOP (DGV) | 48	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HF374
SN74AHCT16374DGVR.A	Active	Production	TVSOP (DGV) | 48	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HF374
SN74AHCT16374DL	Obsolete	Production	SSOP (DL) | 48	-	-	Call TI	Call TI	-40 to 85	AHCT16374
SN74AHCT16374DLR	Active	Production	SSOP (DL) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT16374
SN74AHCT16374DLR.A	Active	Production	SSOP (DL) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT16374

(1) Status: For more details on status, see our product life cycle.

(2) Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT16374DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74AHCT16374DGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74AHCT16374DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

PACKAGE MATERIALS INFORMATION

TAPE AND REEL BOX DIMENSIONS

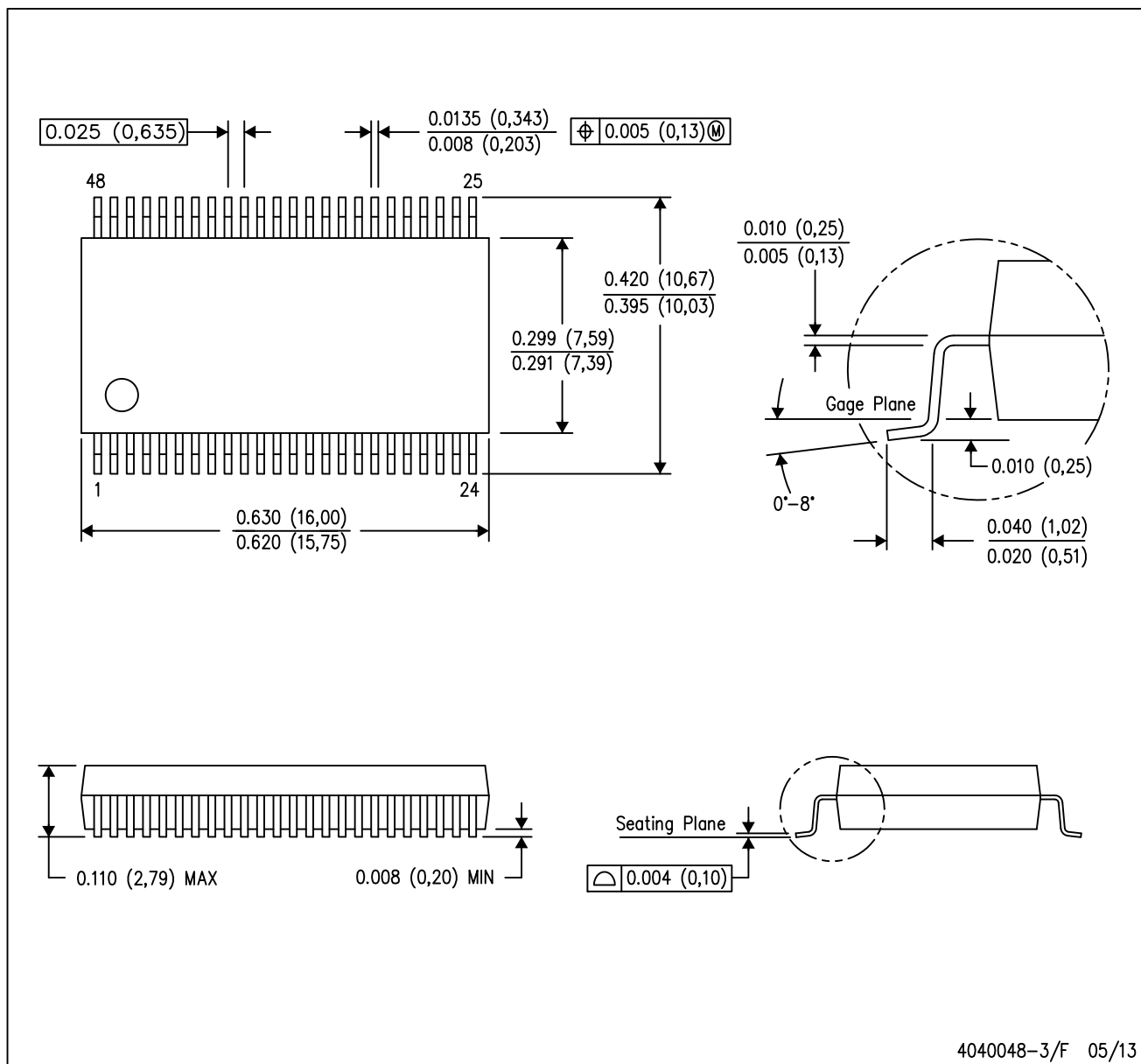

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT16374DGGR	TSSOP	DGG	48	2000	356.0	356.0	45.0
SN74AHCT16374DGVR	TVSOP	DGV	48	2000	353.0	353.0	32.0
SN74AHCT16374DLR	SSOP	DL	48	1000	356.0	356.0	53.0

DL (R−PDSO−G48)   PLASTIC SMALL−OUTLINE PACKAGE

4040048−3/F 05/13

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
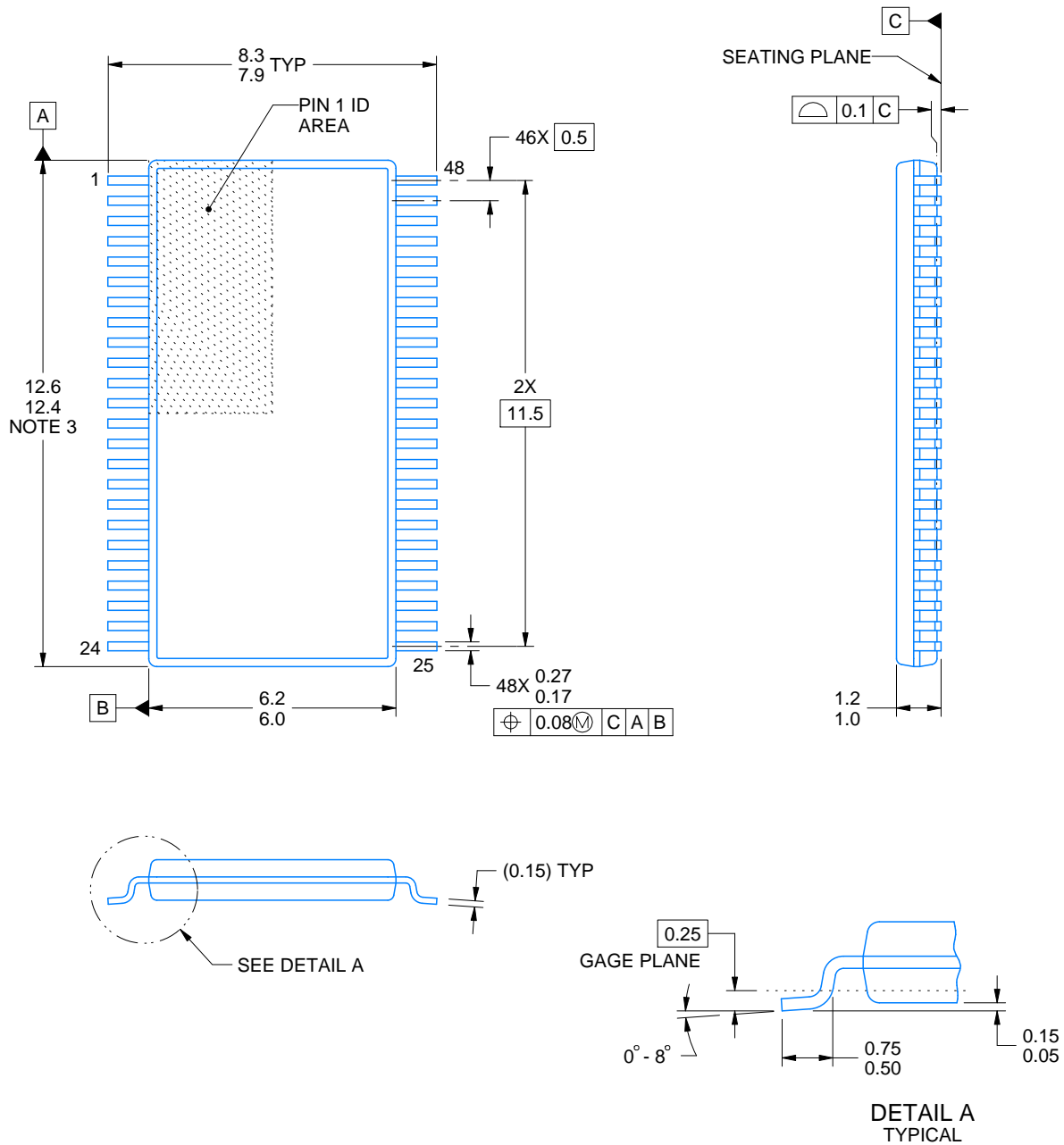   D. Falls within JEDEC MO−118

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DGV (R-PDSO-G)**   **PLASTIC SMALL-OUTLINE**

24 PINS SHOWN

DIM \ PINS **	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

NOTES: A. All linear dimensions are in millimeters.
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
        D. Falls within JEDEC: 24/48 Pins – MO-153
                             14/16/20/56 Pins – MO-194

8.3 / 7.9 TYP

A

PIN 1 ID AREA

1

46X 0.5

48

12.6 / 12.4 NOTE 3

2X 11.5

24

25

B

6.2 / 6.0

48X 0.27 / 0.17

$\oplus$ 0.08 Ⓜ C A B

C

SEATING PLANE

⌒ 0.1 C

1.2 / 1.0

(0.15) TYP

SEE DETAIL A

0.25

GAGE PLANE

0° - 8°

0.75 / 0.50

0.15 / 0.05

DETAIL A
TYPICAL

4214859/B   11/2020

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

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48X (1.5)

1

48X (0.3)

46X (0.5)

(R0.05)
TYP

SYMM

48

SYMM

24

25

(7.5)
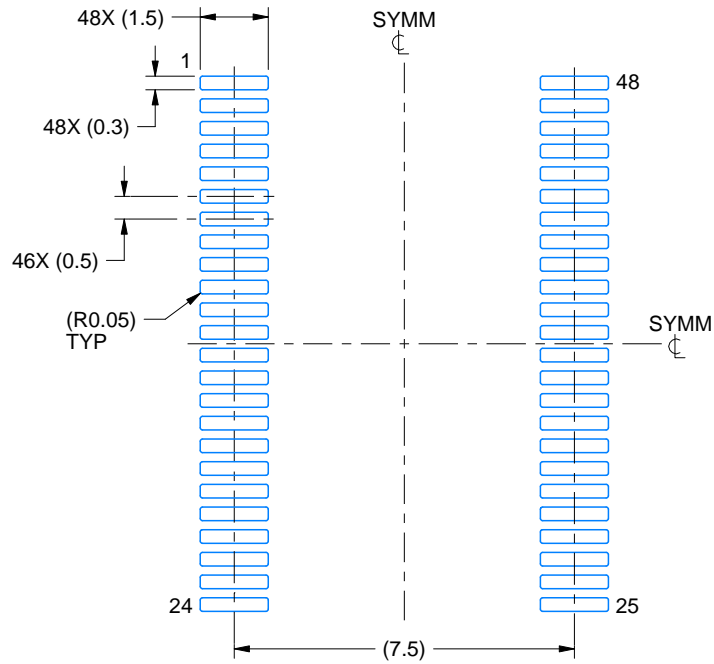
LAND PATTERN EXAMPLE
SCALE:6X

SOLDER MASK
OPENING

METAL

0.05 MAX
ALL AROUND

**NON SOLDER MASK
DEFINED**

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

0.05 MIN
ALL AROUND

**SOLDER MASK
DEFINED**
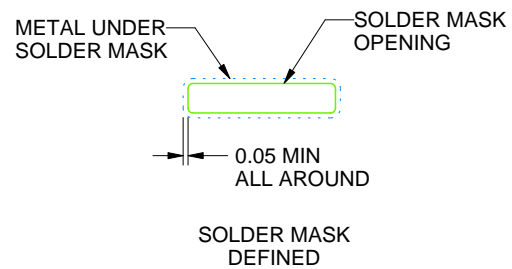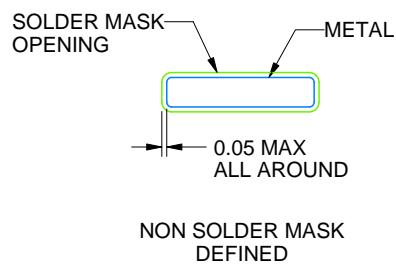
SOLDER MASK DETAILS

4214859/B   11/2020

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

48X (1.5)

1

48X (0.3)

46X (0.5)

(R0.05) TYP

SYMM

SYMM

48

25

24

1

(7.5)
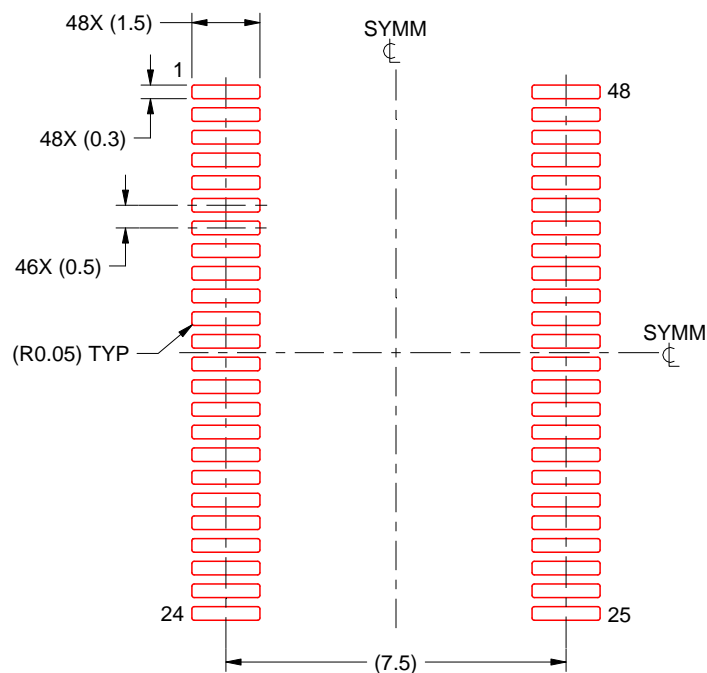
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4214859/B   11/2020

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate
   design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN

PINS ** DIM	48	56	64
A MAX	12,60	14,10	17,10
A MIN	12,40	13,90	16,90

4040078 / F 12/97

NOTES: A. All linear dimensions are in millimeters.
           B. This drawing is subject to change without notice.
           C. Body dimensions do not include mold protrusion not to exceed 0,15.
           D. Falls within JEDEC MO-153

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